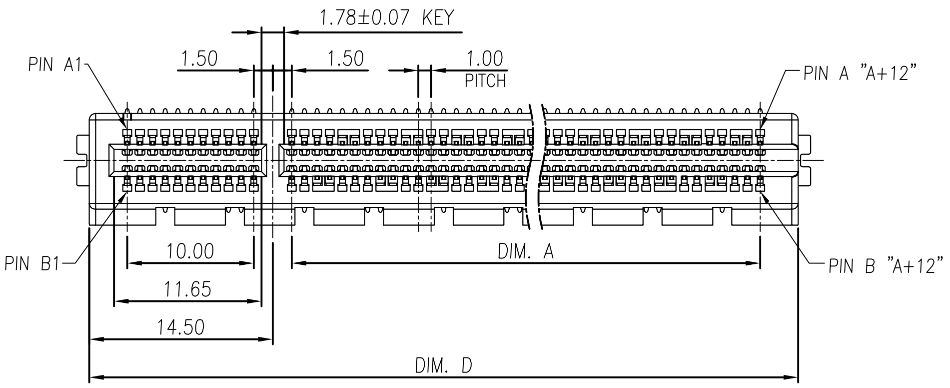
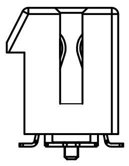
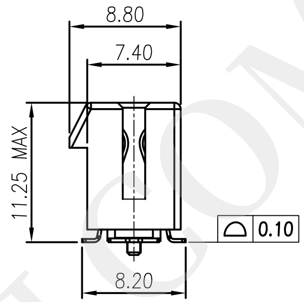
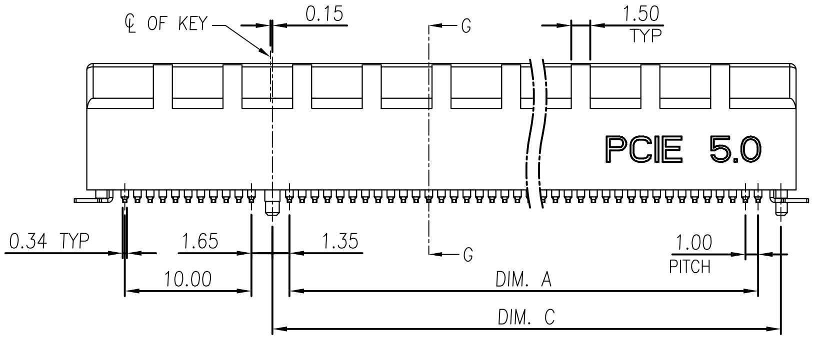




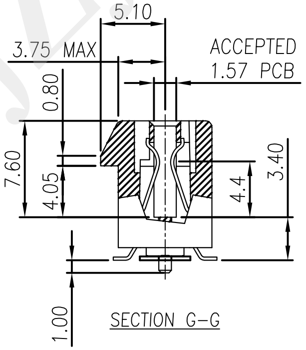
WITH RIDGE

DIMENSIONS				
POSITION	A±0.20	C±0.25	D±0.25	E±0.30
36	6.0	9.15	25.0	27.0
64	20.0	23.15	39.0	41.0
98	37.0	40.15	56.0	58.0
164	70.0	73.15	89.0	91.0

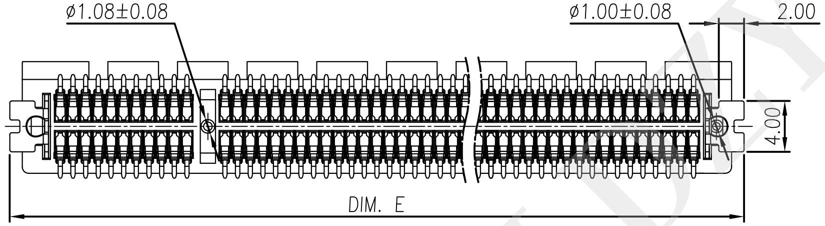




NOTES:
1. MATERIAL:
  1.1 HOUSING: THERMOPLASTIC, HIGH TEMP, UL94V-0, COLOR:BLACK
  1.2 CONTACTS: COPPER ALLOY.
  1.3 PAD: COPPER ALLOY.
  1.4 CAP: THERMOPLASTIC, HIGH TEMP, UL94V-0, COLOR: BLACK.
2. FINISH:
  2.1 CONTACT:
    SELECTIVE GOLD PLATING ON THE CONTACT AREA.
    100μ" MIN. MATTE-TIN PLATING ON THE SOLDERTAILS,
    50μ" MIN. NICKEL UNDERPLATING OVERALL.
  2.2 PAD:
    100μ" MIN. MATTE-TIN PLATING WITH 50μ" MIN.
    NICKEL UNDERPLATE OVERALL.



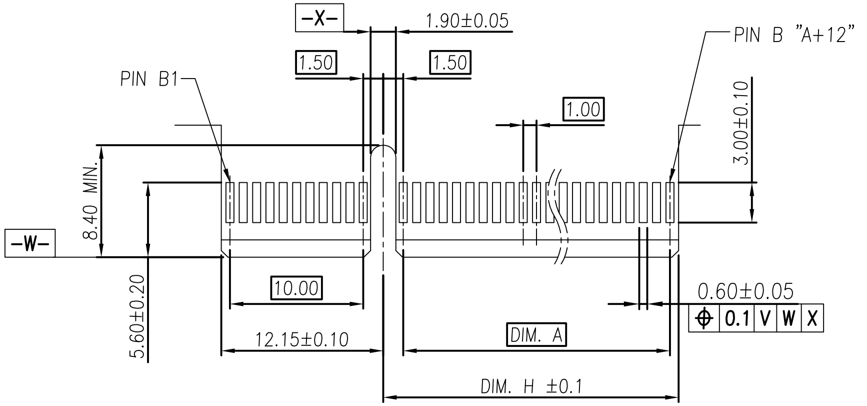
SECTION G-G

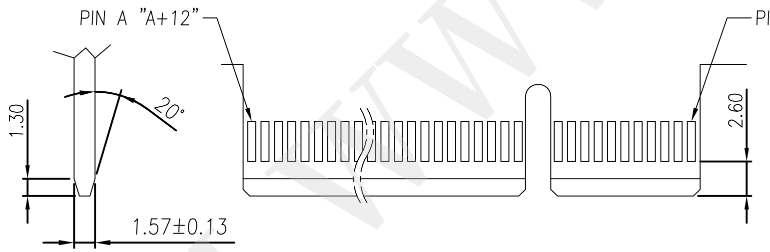


HOAUC

深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.° ±2° X.X° ±0.5°	DRAWED BY : 陈一鸣	DATE : 2014-02-23	PART NAME: PCI-E Gen 5.0 立贴 侧面开槽
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYC58-PCIXX-112 MOLD NO.
UNIT: mm [inch]	APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO: HYC-2606041051
SCALE:1:1 SIZE: A4			SHEET NO. 1 OF 1





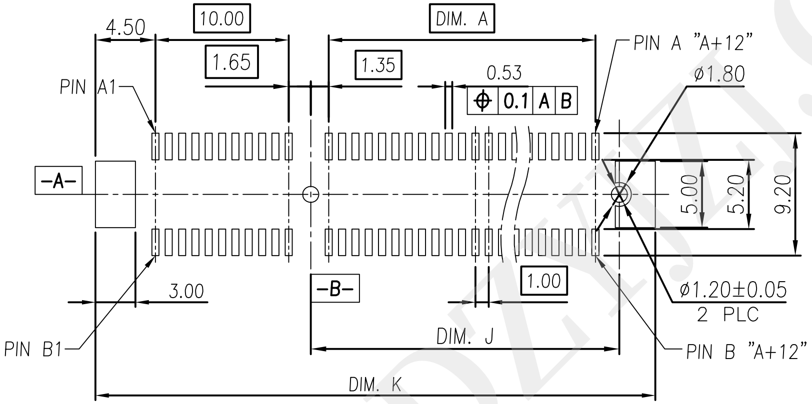
SECONDARY (SOLDER) SIDE

← I/O PANEL DIRECTION

PRIMARY (COMPONENT) SIDE

NOTES:

CHAMFER EDGE MUST BE FREE OF CUTTING BURRS



RECOMMENDED PCB LAYOUT

(COMPONENT SIDE)

TOLERANCE: ±0.05

POSITION	DIM. A	DIM. H	DIM. J	DIM. K
36	6.0	8.15	9.15	28.0
64	20.0	22.15	23.15	42.0
98	37.0	39.15	40.15	59.0
164	70.0	72.15	73.15	92.0

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TOLERANCE:
X.X ±0.30
X.XX ±0.25
X.XXX ±0.15
X.° ±2° X.X° ±0.5°

UNIT: mm [inch]

SCALE:1:1 SIZE: A4

DRAWED BY : 陈一鸣	DATE : 2014-02-23	PART NAME: PCI-E Gen 5.0 立贴 侧面开槽
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APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO: HYC-2606041051
		SHEET NO. 1 OF 1